



# **Product Change Notification**

## **113650 - 00**

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# Product Change Notification

**Change Notification #:** 113650 - 00  
**Change Title:** Intel® SSD DC S3500 Series (80GB, 120GB, 340GB M.2 80mm SATA 6Gb/s, 20nm, MLC)  
PCN 113650-00  
Product Design  
New Design M.2 MOQ100 PKG KIT  
**Date of Publication:** March 6, 2015

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	<b>March 20, 2015</b>
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## Description of Change to the Customer:

New Design implemented for the M.2 MOQ100 Packaging Kit. Summary Below

- PKG KIT IPN dash-up from H37252-001 to H37252-002
- CLAMSHELL (bottom) dash-up from H37248-001 to H37248-002
- CLAMSHELL (top) dash-up from H37249-001 to H37249-002
- Old Top Foam H614601-001 removed
- Old Bottom Foam H61459-001 removed
- ESD Bag changing from G68129-001 to H70963-001
- Disti box changing from G94040-001 to H71489-001

Old M.2 MOQ100 Packaging Kit required the insertion of Top and Bottom foam in the clamshell that held the 100 M.2 drives to stabilize and reduce movement during shipping.

The new clamshell has been redesigned so that the top and bottom foam is no longer required.

See below for new packaging details:

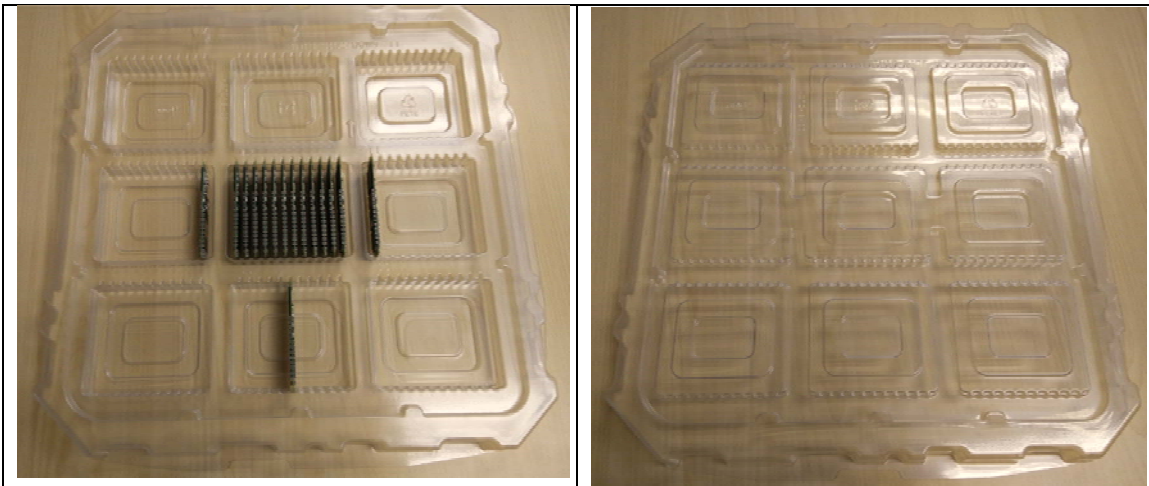
Old Clamshell with Foam:  
Bottom: H37248-001

Top: H37249-001



New Clamshell without Foam:  
Bottom: H37248-002

Top: H37249-002



Old ESD Bag & Disti Box:  
G68129-001

G94040-001



## New ESD Bag & Disti Box:



### **Customer Impact of Change and Recommended Action:**

There is no customer impact as this change is to the design of the MOQ100 packaging kit.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

### **Products Affected / Intel Ordering Codes:**

Product Code	MM#	Pre Change TA	Post Change TA
SSDSCKHB080G4	932261	H25291-200	H25291-201
SSDSCKHB120G4	932262	H25294-200	H25294-201
SSDSCKHB340G4	932263	H25297-200	H25297-201

### **PCN Revision History:**

**Date of Revision:**

March 6, 2015

**Revision Number:**

00

**Reason:**

Originally Published PCN